The products are 10MBd high-speed opto-couplers in a plastic WSOP8 package. The device consists of a high efficient AlGaAs Light Emitting Diode and a high speed optical detector. This design provides excellent AC and DC isolation between the input and output sides of the optocoupler. The output of the optical detector features an open collector Schottky clamped transistor. The ` SM H ete ā rplscal ċ % ƥ

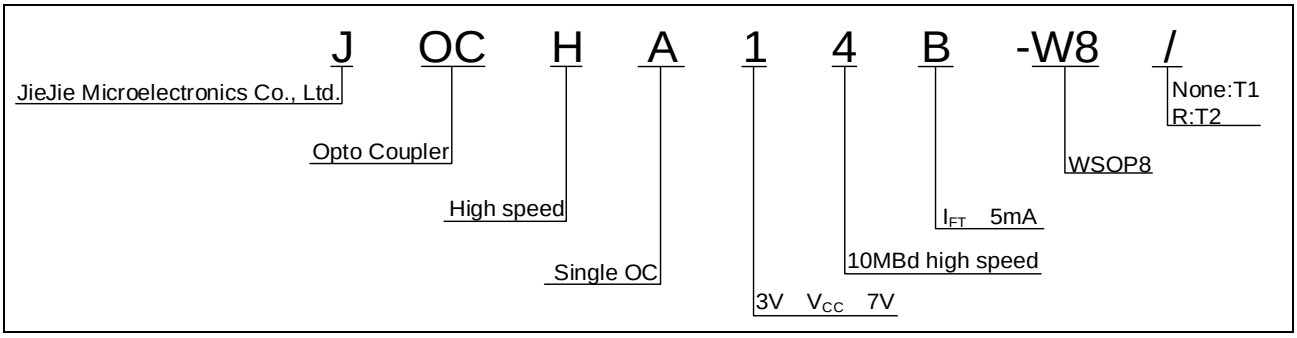
(Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Input Power Dissipation	P_D	100	mW

	Isolation Resistance	R_{ISO}	DC500V 40~60%R.H.	-	10^{12}	-	Ω
	Floating Capacitance	C_{IO}	V=0, f=1MHz	-	1	-	pF
Switching Characteristics	Trigger LED Current	I_{FT}	V_{CC}=5V V_O=V_{OL}	-	-	5	mA
	Propagation Delay Time to Logic Low	t_{PHL}	C_L=15pF, R_L=350Ω, I_F=7.5mA	-	-	60	ns
	Propagation Delay Time to Logic High	t_{PLH}		-	-	60	ns
	Pulse width distortion	$\|t_{PHL}-t_{PLH}\|$		-	-	35	ns
	Common Mode Transient Immunity at Logic High	CM_H	V_{CC}=3.3V, I_F=0mA, V_{CM}=1000V, R_L=350Ω	10	15	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM_L	V_{CC}=3.3V, I_F=10mA, V_{CM}=1000V, R_L=350Ω	10	15	-	kV/μs
	Rise Time	tr	C_L=15pF, R_L=350Ω, I_F=7.5mA	-	30	-	ns
	Fall Time	tf		-	30	-	ns

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Operating Temperature	T_a	-40	-	85	
Supply Voltage	V_{CC}	2.7	-	3.6	V
		4.5	-	5.5	
Low Level Input Current	I_{FL}	0	-	250	μA
High Level Input Current	I_{FH}	7	-	15	mA

Output Pull-up Resistor	R_L	330	-	4k	Ω
Fan Out (at R_L=1kΩ per channel)	N	-	-	5	TTL Loads



None/R	1200 Units/Reel

FIG.1: High Level Output Current vs. Ambient Temperature

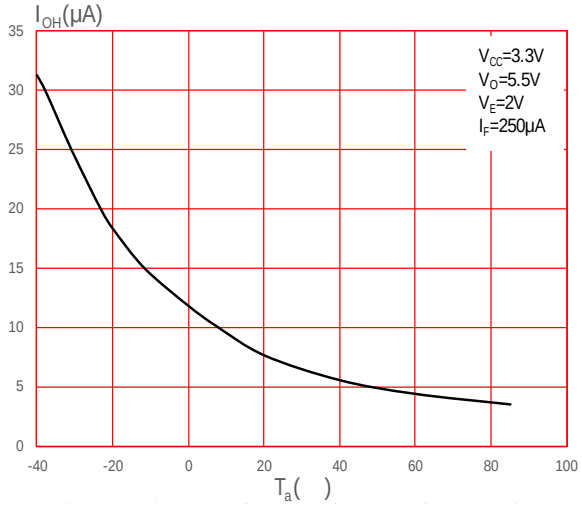


FIG.2: High Level Output Current vs. Ambient Temperature

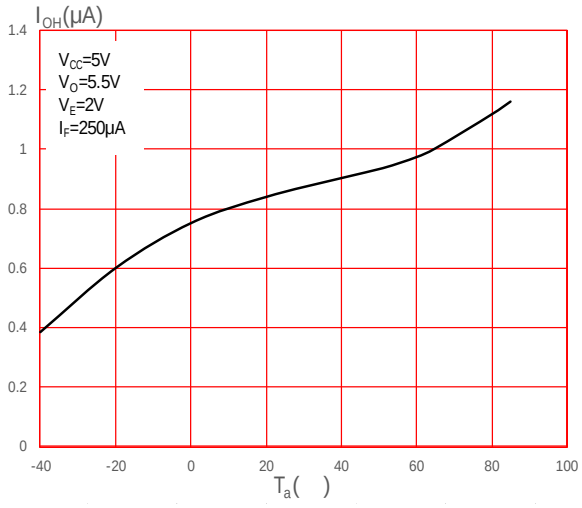


FIG.3: Input Threshold Current vs. Ambient Temperature

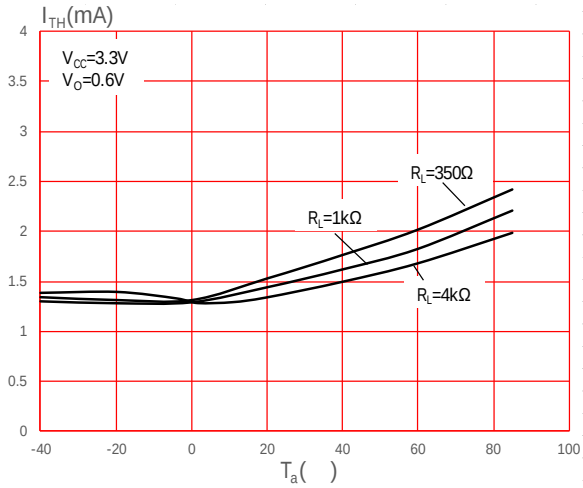


FIG.4: Input Threshold Current vs. Ambient Temperature

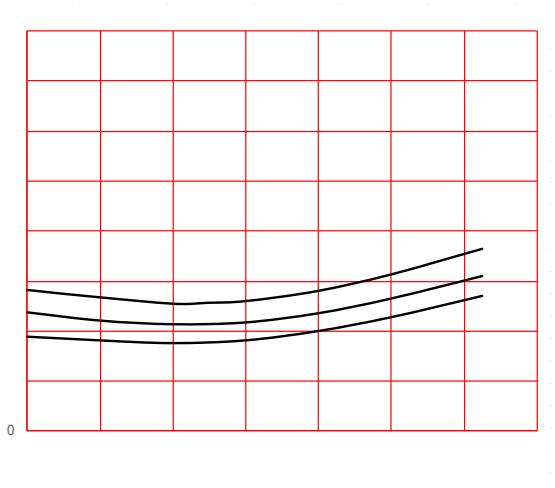


FIG.7: Low Level Output Current vs. Ambient Temperature

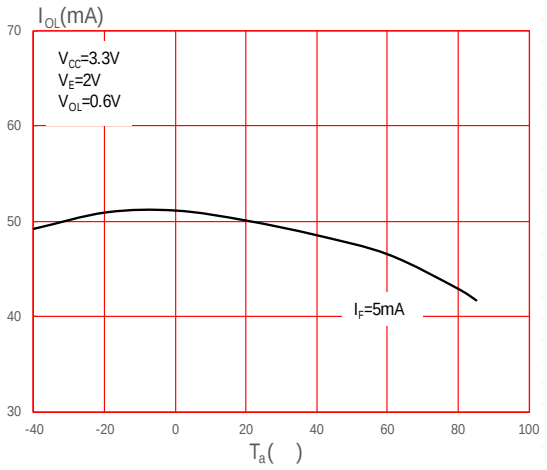


FIG.8: Low Level Output Current vs. Ambient Temperature

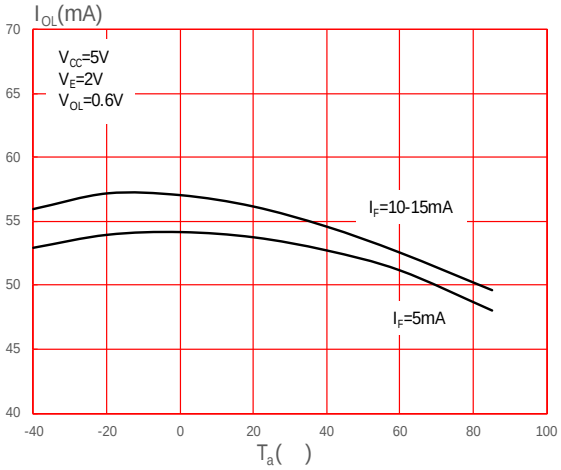


FIG.9: Input Forward Voltage vs. Input Forward Current

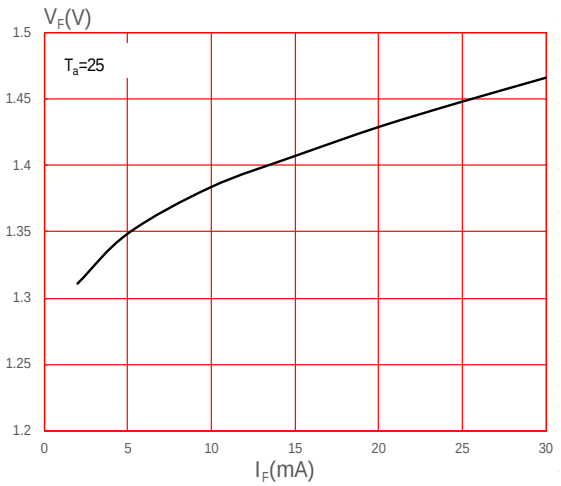


FIG.10: Forward Voltage vs. Ambient Temperature

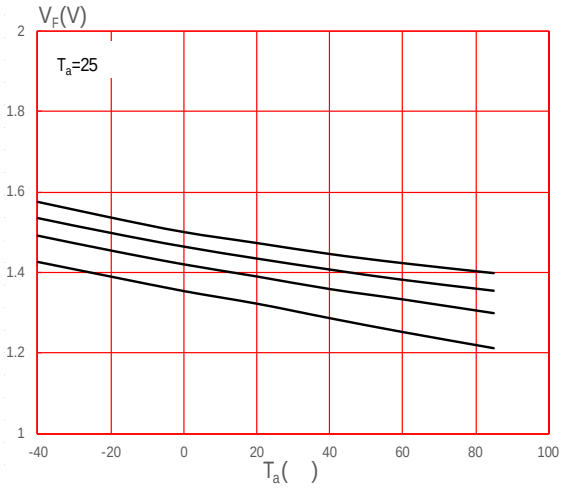


FIG.13: Pulse Width Distortion vs. Ambient Temperature

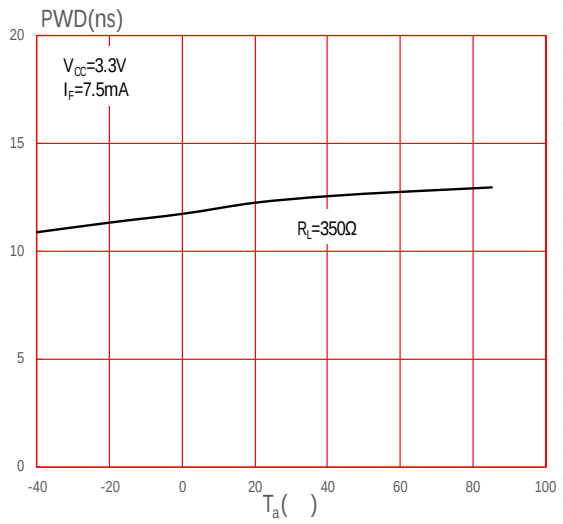


FIG.14: Pulse Width Distortion vs. Ambient Temperature

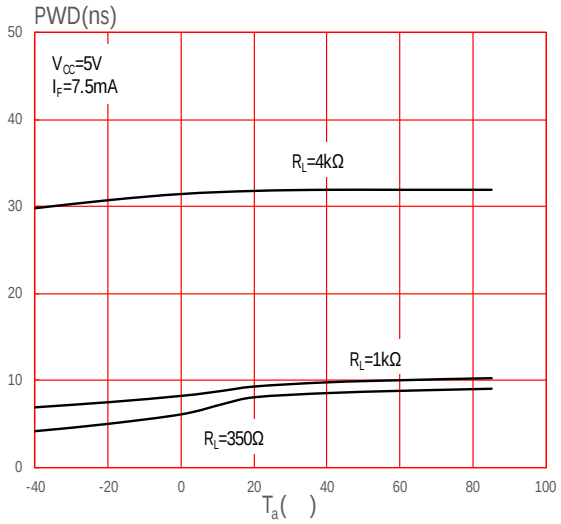
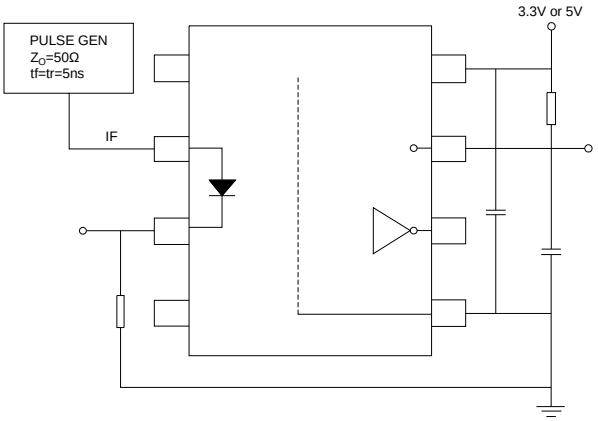
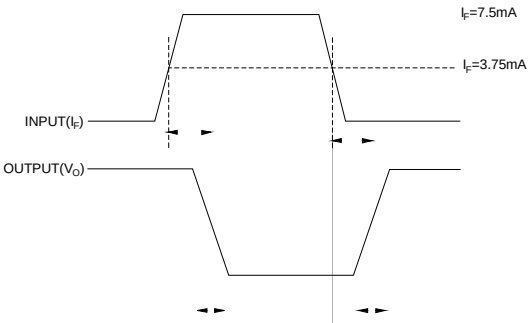
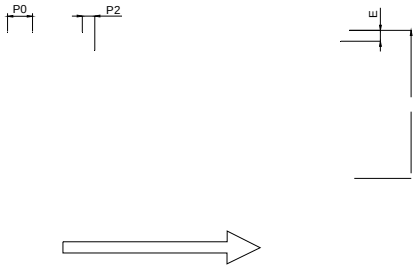


Fig.15: Test Circuit for TPHL and TPLH





Ref.	Dimensions							
	Millimeters			Inches				
	Min.	Typ.	Max.	Min.	Typ.	Max.		
A	13.50		13.70	0.531		0.539		
B	6.15		6.35	0.21	ş	0.250	66	T
C								
D	3.50		3.70			0.146		
E	14.71		15.31			0.603		
F	0.52			0.020				
G	16.36		16.86			0.664		
H	0.10		0.40			0.016		
I	3.65			0.144				
J			0.607	0.012				
K								


P0
P2
E

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1